

Timothy Wai Pui WU/PLAND

寄件者: Winnie Tsang <[REDACTED]>
寄件日期: 2026年06月12日星期五 16:48
收件者: Timothy Wai Pui WU/PLAND
主旨: RE: Planning Application No. A/NE-TKLN/133
附件: 打鼓嶺北地段Lot 330, 332號_從公眾路入到申請地方指引.pdf; Carpark design planning_2026.pdf; From Public road to the Application Site_20260612.pdf

類別: Internet Email

Dear Timothy,

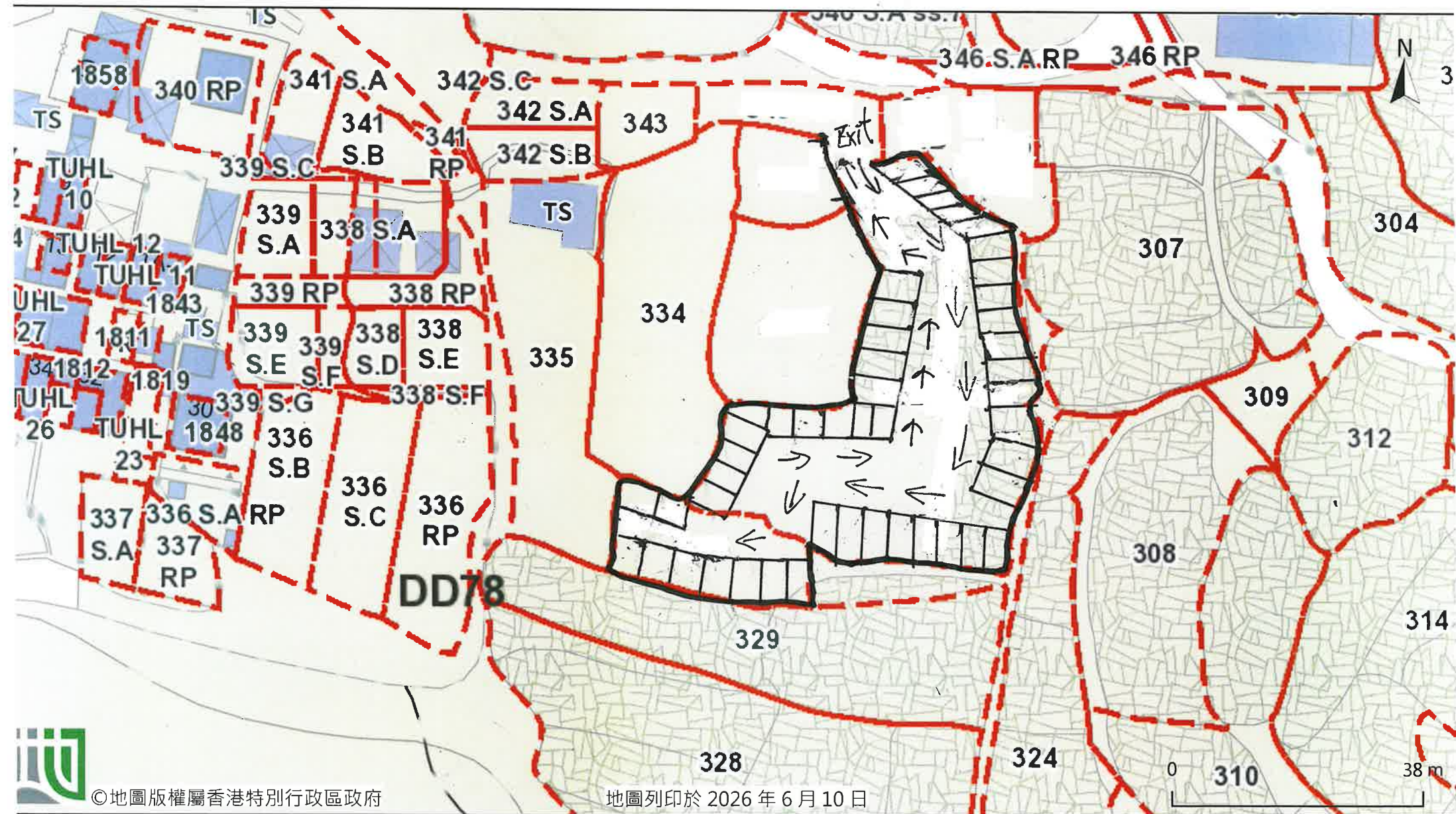
As the requisition, please find the details as below:

- 1.) the materials for the proposed land filling and its purpose. >> use鋪設碎石或瀝青（柏油）
- 2.) it is noted that the submitted layout plan indicates the boundary beyond Lots 330 and 332 in D.D. 78. Please clarify. (as attached)
- 3.) Please indicate the connectivity from public road to the application site. (as attached)

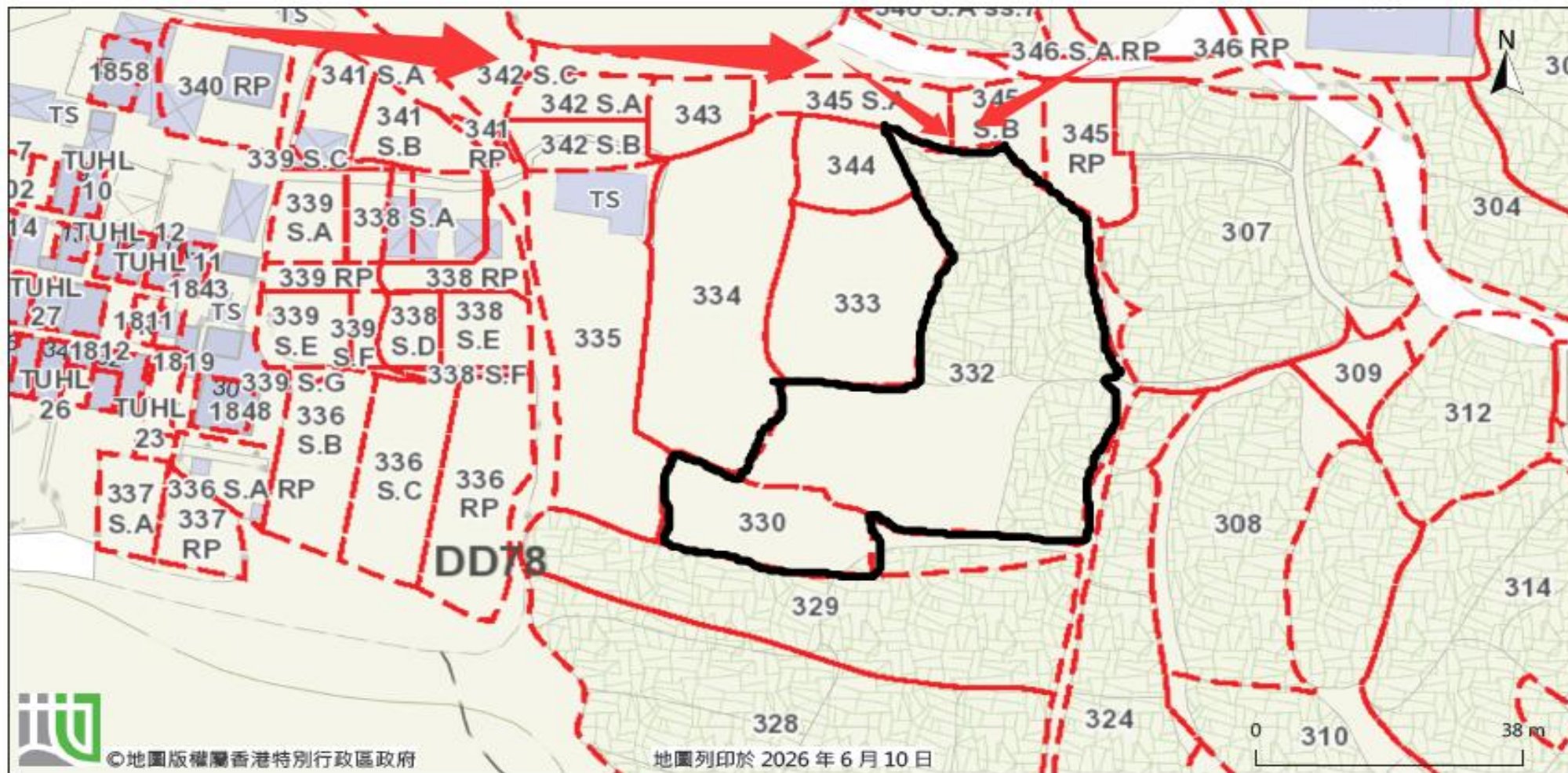
Btw, for the whole area clarification, we will be enclosed with 6-foot-high barbed wire.

Thanks & Best regards,
Winnie
Consinee Group Co., Ltd.

[REDACTED]



➤ From public road to the application site



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➤ 從蓮麻坑路旁邊的車路進入



➤ 從旁邊道路再進入



➤ 從旁邊小路進入



➤ 轉回看的行車指示



➤ 從後面直入裡面申請地方

